

# OCtoPus 2EE

HPC - BIG DATA - CLOUD  
21" - 10U - 2 nodes - 4 CPUs per server

## Key Features

21" - 10U - 2 nodes

Dual AMD EPYC™  
7xx2 and 7xx3 Series  
Socket SP3

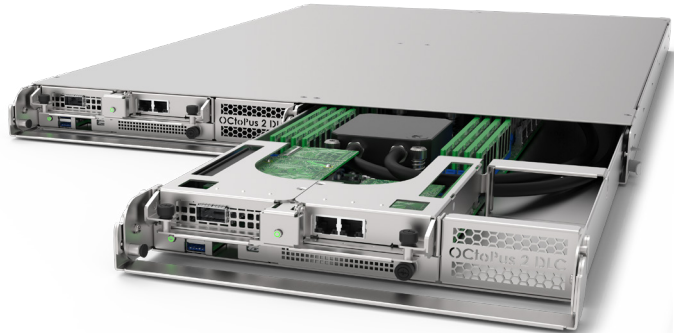
16x DDR4 @ 3200MHz

PCIe 4.0 x16

OCP technology  
12V DC

IPMI  
IPMI with Aspeed®  
AST2500

Direct liquid cooling



### Direct liquid cooling ready

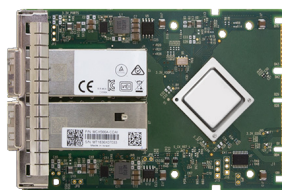
OCtoPus DLC solutions servers are equipped with leak-proof blind mate connectors to attach to the manifolds. No more pipes to disconnect during maintenance, just pull the server back to remove it.

### Bring high density to the next level !

This is an ultra-dense 1 OU solution consisting of a 2-node drawer. This modular design allows for great scalability and enables the most demanding workloads to be considered with **1960W of computing power per OU.**

### 3<sup>rd</sup> Gen AMD® EPYC® Processors

The OCtoPus 2EE was built to elevate your business productivity with AMD EPYC™ - the world's highest performing x86 server processors. With a broad and growing ecosystem, AMD EPYC™ Processors deliver the highest per-core performance to ensure fast time-to-value for your business.



### OCP NIC 3.0

Go dense and scale easily thanks to OCP 3.0 Network capabilities.



## SPECIFICATIONS

<b>System</b>	<b>Model</b>	OCtoPus 2EE
	<b>Form Factor</b>	19"- 10U
	<b>Nodes</b>	2
	<b>Server dimension</b>	880 x 537 x 43mm (D x W x H)
	<b>Node dimension</b>	880 x 265 x 43 mm (D x W x H)
<b>Storage</b>	<b>Internal type</b>	Per node: 2x M.2 (Gen4 x4 link, up to 2280, PCIe, SATA); Form factor: 22110/2280 [CPU0]
	<b>Front Hot swaps</b>	Per node: Up to 5x 2.5" Hot-swap Storage Bays (SATA/SAS/NVMeSupported)
<b>Motherboard</b>	<b>CPU</b>	Dual socket SP3 (LGA 4094) AMD EPYC™ 7xx2 and 7xx3 Series Processor family
	<b>Chipset</b>	Per Node: System on chip
	<b>Expansion slots</b>	Per Node: 2x PCIe x16 (Gen4 x16 link), LP, HL 1x OCP 3.0 Mezzanine (Gen4 x16 link)
	<b>BMC</b>	ASPEED AST2500
<b>Memory</b>	<b>Total Slots</b>	Per node: 16 (8-channel per CPU, 8 DIMM per CPU)
	<b>Capacity per DIMM</b>	Maximum up to 64GB (with RDIMM modules) Maximum up to 128GB (with LRDIMM modules) Maximum up to 256GB (with 3DS RDIMM / LRDIMM modules)
<b>Network</b>		1 x Realtek RTL8211E for dedicated management GLAN 1x OCP NIC 3.0 (PCIe4.0 x16) Options available: 2x 25GbE (SFP28) 2x 100GbE (QSFP56 / QSFP28) 2x 200GbE (QSFP56)
<b>Front I/O</b>	<b>Ports</b>	Per Node: 2x USB 3.2 Gen1 type A 1x mini display port 2x ports via OCP NIC 3.0 1x RJ-45 Management port
	<b>Switch/LED</b>	Per Node: 1x Power Switch/LED 1x ID LED
<b>Management Solution</b>	<b>Out of Band Remote Management</b>	BMC Remote control based on Aspeed® AST2500 remote management controller (Power Control Configuration, Chassis Identify, Boot Option, iKVM, BMC Account Configuration)
<b>Power input</b>	<b>Type</b>	OCP technology 12V DC